

WHAT IS CLAIMED IS:

1. A heat-dispersing module of an electronic device, comprising:
 - a housing having a top surface, a bottom surface, a first side surface and a second side surface, wherein said first side surface is opposite to said second side surface;
 - a heat-dispersing fan mounted on said first side surface of said housing;
 - a first vent area disposed on said second side surface of said housing;
 - a second vent area disposed on said top surface of said housing; and
 - a printed circuit board positioned in said housing, thereby a first airflow channel is formed between said top surface of said housing and said printed circuit board, and a second airflow channel is formed between said bottom surface of said housing and said printed circuit board,wherein said printed circuit board produces a relatively higher heat at said second airflow channel than said first airflow channel and a distance of said second airflow channel from said printed circuit board to said bottom surface is relatively larger than that of said first airflow channel from said printed circuit board to said top surface.
2. The heat-dispersing module as claimed in claim 1 wherein said electronic device is a power supply.
3. The heat-dispersing module as claimed in claim 1 wherein said first side surface of said housing comprises a meshed portion.
4. The heat-dispersing module as claimed in claim 3 wherein said heat-dispersing fan is positioned above said meshed portion.
5. The heat-dispersing module as claimed in claim 1 wherein said printed circuit board comprises a first surface and a second surface, said first surface is located within said second airflow channel, and a number of electronic

elements located on said first surface is relatively larger than that on said second surface.

6. The heat-dispersing module as claimed in claim 5, further comprising at least a heat conducting plate, wherein said heat conducting plate diverts the heat produced by said printed circuit board to said bottom surface of said housing.

7. The heat-dispersing module as claimed in claim 6 wherein one end of said heat conducting plate is fixed on said first surface of said printed circuit board and the other end is contacted with said bottom surface of said housing.

8. The heat-dispersing module as claimed in claim 7 wherein said heat conducting plate is fixed on said bottom surface of said housing via a screw.

9. The heat-dispersing module as claimed in claim 6 wherein one end of said heat conducting plate is fixed on said first surface of said printed circuit board, and said heat diverted by said heat conducting plate is conducted through a conducting medium between the other end of said heat conducting plate and said bottom surface of said housing.

10. The heat-dispersing module as claimed in claim 5 further comprising at least a heat sink fixed on said first surface of said printed circuit board through one end thereof.

11. The heat-dispersing module as claimed in claim 1 wherein a distance between said printed circuit board and said top surface of said housing is ranged from 10 to 50 nm.

12. A heat-dispersing module of an electronic device, comprising:
a housing having a top surface, a bottom surface, a first side surface and a second side surface, wherein said first side surface is opposite to said second side surface;

a heat-dispersing fan mounted on said first side surface of said housing;
a first vent area disposed on said second side surface of said housing;
a second vent area disposed mounted on said top surface of said housing;
a printed circuit board positioned in said housing, thereby a first airflow channel is formed between said top surface of said housing and said printed circuit board, and a second airflow channel is formed between said bottom surface of said housing and said printed circuit board, wherein said printed circuit board produces a relatively higher heat at said second airflow channel than at said first airflow channel; and

at least a heat conducting plate located within said second airflow channel for diverting a heat produced by said printed circuit board to said bottom surface of said housing.

13. The heat-dispersing module as claimed in claim 12 wherein said electronic device is a power supply.

14. The heat-dispersing module as claimed in claim 12 wherein said first side surface of said housing comprises a meshed portion.

15. The heat-dispersing module as claimed in claim 14 wherein said heat-dispersing fan is positioned above said meshed portion.

16. The heat-dispersing module as claimed in claim 12 wherein said printed circuit board comprises a first surface and a second surface, said first surface is located within said second airflow channel, and a number of electronic elements located on said first surface is relatively larger than that on said second surface.

17. The heat-dispersing module as claimed in claim 16 wherein one end of said heat conducting plate is fixed on said first surface of said printed circuit board and the other end is contacted with said bottom surface of said housing.

18. The heat-dispersing module as claimed in claim 17 wherein said heat conducting plate is fixed on said bottom surface of said housing via a screw.

19. The heat-dispersing module as claimed in claim 16 wherein one end of said heat conducting plate is fixed on said first surface of said printed circuit board, and said heat diverted by said heat conducting plate is conducted through a conducting medium between the other end of said heat conducting plate and said bottom surface of said housing.

20. The heat-dispersing module as claimed in claim 12 wherein a distance of said second airflow channel from said printed circuit board to said bottom surface is relatively larger than that of said first airflow channel from said printed circuit board to said top surface.